

Model Number: K618

- Recommend for Intel® Xeon® Processor E3 Family, Socket LGA1155
Xeon® Processor 3000 Sequence, Socket LGA1156
- Passive Heat Sink for 2U Server

Overall Specification:

- Dimension: 90.0 x 90.0 x 66.0mm
- Weight: 490g
- Copper Base with Aluminum Stacked Fin plus 3 Heat Pipes
- Back Strip is Included
- Thermal Grease Pre-Printed with GE-Toshiba TIG830SP
- Support CPU Power up to 95 Watts

Heatsink K618 Thermal Performance VS. Wind Tunnel Airflow :

